

3A, 100V - 200V Ultra Fast Surface Mount Rectifier

FEATURES

- Planar technology
- Low power loss, high efficiency
- Ideal for automated placement
- Wettable flank
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- High frequency switching
- DC/DC
- Snubber

MECHANICAL DATA

- Case: TO-277A (SMPC4.6U)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.102g (approximately)

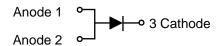
KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I _F	3	Α	
V_{RRM}	100 - 200	V	
I _{FSM}	85	Α	
T_{JMAX}	175	°C	
Package	TO-277A (SMPC4.6U)		
Configuration	Single die		







TO-277A (SMPC4.6U)



PARAMETER		SYMBOL	PUUP3B	PUUP3D	UNIT
Marking code on the device			PU3BH	PU3DH	
Repetitive peak reverse voltage		V_{RRM}	100	200	V
Reverse voltage, total rms value		V _{R(RMS)}	70	140	V
Forward current		I _F	3		Α
Surge peak forward current single half	t = 8.3ms	,	85		A
sine-wave superimposed on rated load	t = 1.0ms	IFSM	190		
Junction temperature		TJ	-55 to +175		°C
Storage temperature		T _{STG}	-55 to	+175	°C



THERMAL PERFORMANCE			
PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance ⁽¹⁾	$R_{\Theta JL}$	2.0	°C/W
Junction-to-ambient thermal resistance ⁽²⁾	$R_{\Theta JA}$	52.4	°C/W
Junction-to-case thermal resistance ⁽²⁾	R _{eJC}	11.4	°C/W

Thermal Performance Notes:

- 1. With ideal heat sink
- 2. Units mounted on PCB (16mm x 16mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER CONDITIONS		SYMBOL	TYP	MAX	UNIT
	I _F = 1.5A, T _J = 25°C		0.81	-	V
F (1)	I _F = 3.0A, T _J = 25°C	\/	0.86	0.93	V
Forward voltage ⁽¹⁾	I _F = 1.5A, T _J = 125°C	V _F	0.66	-	V
	I _F = 3.0A, T _J = 125°C		0.73	-	V
D (2)	T _J = 25°C		-	2	μA
Reverse current @ rated V _R ⁽²⁾	T _J = 125°C	l _R	-	10	μA
Junction capacitance	$1MHz, V_R = 4.0V$	CJ	47	-	pF
Payaraa raaayary tima	$I_F = 0.5A$, $I_R = 1.0A$, $I_{rr} = 0.25A$	4	-	25	ns
Reverse recovery time	$I_F = 1.0A$, di/dt = 50A/ μ s, $V_R = 30V$	t _{rr}	31	-	
Reverse recovery current		I _{RM}	4.9	-	Α
Reverse recovery charge	$I_F = 3.0A$, di/dt = 200A/ μ s, $V_R = 100V$	Q _{rr}	51	-	nC
Reverse recovery time		t _{rr}	23	-	ns

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION		
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING
PUUP3x	TO-277A (SMPC4.6U)	6,000/ Tape & Reel

Notes:

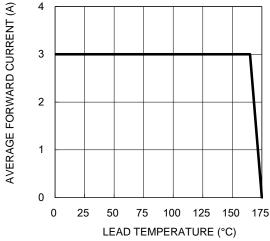
1. "x" defines voltage from 100V(PUUP3B) to 200V(PUUP3D)

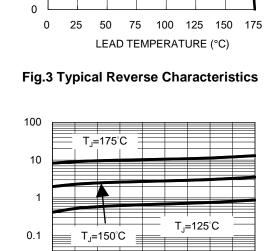


CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve





T₁=25°C

30 40 50 60 70 80 90 100

PERCENT OF RATED PEAK REVERSE VOLTAGE (%)

INSTANTANEOUS REVERSE CURRENT (µA)

0.01

0.001

20

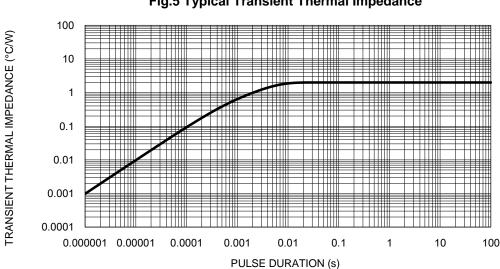


Fig.2 Typical Junction Capacitance

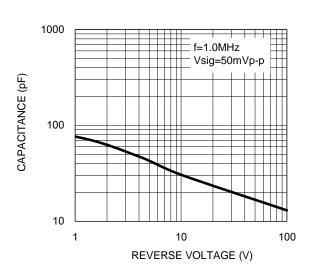


Fig.4 Typical Forward Characteristics

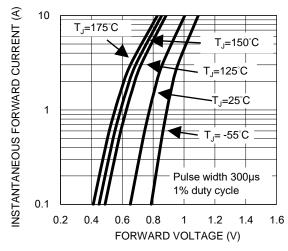
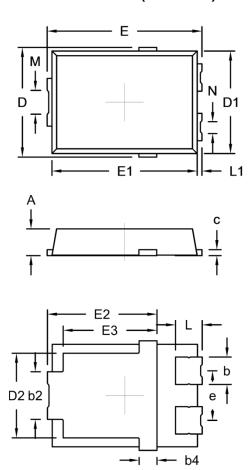


Fig.5 Typical Transient Thermal Impedance



PACKAGE OUTLINE DIMENSIONS

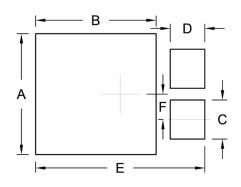
TO-277A (SMPC4.6U)



DIM.	Unit (mm)		Unit ((inch)
DIIVI.	Min.	Max.	Min.	Max.
Α	1.00	1.20	0.039	0.047
b	1.05	1.35	0.041	0.053
b2	1.90	2.20	0.075	0.087
b4	0.75 (0.75 (NOM.)		(NOM.)
С	0.15	0.40	0.006	0.016
D	4.45	4.75	0.175	0.187
D1	4.25	4.35	0.167	0.171
D2	3.40	3.70	0.134	0.146
E	6.35	6.65	0.250	0.262
E1	6.05	6.15	0.238	0.242
E2	4.40	4.80	0.173	0.189
E3	3.94 (NOM.)		0.155	(NOM.)
е	2.08 (NOM.)		0.082	(NOM.)
L	0.94	1.24	0.037	0.049
L1	0.05	0.35	0.002	0.014
М	0.65	1.15	0.026	0.045
N	0.25	0.75	0.010	0.030

Package body size D1 and E1 do not include mold flash Mold flash shall not exceed 0.1mm per side

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	4.95	0.195
В	4.95	0.195
С	1.60	0.063
D	1.42	0.056
E	6.95	0.274
F	1.04	0.041

MARKING DIAGRAM



P/N = Marking Code YW = Date Code F = Factory Code



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